



				ATTY. DOCKET NO. 1875.0370000		APPLICATION N 09/849,537	10.
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.8)		U.S	S. PATENT DOCUMENTS			
EXAMENA AND INITIAL		DOCUMENT NUMBER	DATE	NAME	CLAS	SS SUB- CLASS	FILING DATE
ML	AA1	5,894,410	04/1999	Barrow	361	760	
me	AB1	6,020,637	02/2000	Karnezos	257	738	
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ML	AG1	10-247702	09/1998	Japan	но11	23/12	Yes No
· ·	AH1						Yes No
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	AJ	Englis	sh-language Abst //www1.jpdl.jpo.	ract of JP 10-247702, <u>qo.jp,</u> 2 Pages (last	published Se visited Janua	ptember 14, ry 25, 2002)	1998, from
ML	AJ	Englis http://	sh-language Abst //wwwl.jpdl.jpo.	ract of JP 10-247702, .go.ip, 2 Pages (last	published Se visited Janua	ptember 14, ry 25, 2002)	1998, from
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M	AK	1 1	sh-language Abst	eract of JP 10-247702, go.ip, 2 Pages (last	published Se	ptember 14, ry 25, 2002)	1998, from

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

ATTY. DOCKET NO. APPLICATION NO. 09/849,537

APPLICANT Zhang et al.

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MC	AA1	5,39	7,921	03/19	995	Karn	ezos		257	779		
	AB1	5,474	4,957	12/19	95	Urushima			437	209		
	AC1	5,534	4,467	07/19	996	Rostoker			437	209		
	AD1 /	09/98	34,259			Zhao	et al.				10/29/2001	
0.26/	AE1	09/99	97,272			Zhao	et al.				11/30/2001	
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MC	AN	1	Transaction	s on	Componer	nts, Pa	corn Phenomena in a ackaging, and Manu /ol. 18, No. 3, pp. 4	ıfactur	ing Techno			
MC	AO	1					Packaging: Taking ⁻ g Company, May 19				onic Packaging	
mc	AP	Anderson, L. and Trabucco, B., "Solder Attachment Analysis of Plastic BGA Modules", Surface Mount International Conference, Surface Mount International, August 28-September 1, 1994, San Jose, California, pp. 189-194.										
ML	AQ	1	Andrews, M., "Trends in Ball Grid Array Technology," Ball Grid Array National Symposium, March 29-30, 1995, Dallas, Texas, 10 pages.									
MC	Attarwala, A.I. Dr. and Stierman, R., "Failure Mode Analysis of a 540 Pin Plastic Ball Grid Array", Surface Mount International Conference, Surface Mount International, August 28-September 1, 1994, San Jose, California, pp. 252-257.											
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M		AN	2	Banerji, K., ' Mount Techi	"Dev nolo	elopment o gy, July 199	of the 94, p	e Slightly Larger Thar p. 21-26.	ı IC Carrie	er (SLI	CC), Journa	al of Surface	
	-	AO	<u>2</u>	Bauer, C., Pl Journal of Si	h.D., urfac	, "Partitioni ce Mount Te	ng ai echn	nd Die Selection Strat ology, October 1994,	tegies for pp. 4-9.	Cost E	Effective Mo	CM Designs",	
		АР	2	Bernier, W.E Components Internationa	. et s", Si II, Au	al., "BGA v urface Mou ugust 28-Se	s. QF nt In pten	P: A Summary of Tra ternational Conferen hber1, 1994, San Jose	adeoffs fo ce Procee e, Califorr	r Seled dings, nia, pp	ction of Hic Surface M . 181-185.	gh I/O ount	
	/	AQ	2	Burgos, J. et al., "Achieving Accurate Thermal Characterization Using a CFD Code A Case Study of Plastic Packages", IEEE Transactions on Components, Packaging, and Manufacturing Technology Part A, IEEE, December 1995, Vol. 18, No. 4, pp. 732-738.									
MC		AR /	2	Chadima, M. Symposium,	., "Ir Dali	nterconnect las, Texas,	ing S Marc	Structure Manufacturi h 29-30, 1995.	ing Techn	ology,	" Ball Grid	Array National	
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	AO	<u>3</u>	Chung, T.C Array Natio	. et a nal S	I., "Rework ymposium	of F Proc	Plastic, Ceramic, and eedings, Dallas, Tex	l Tape Ball kas, March	Grid A 29-30,	rray Assem 1995, pp.	iblies", Ball Grid 1-15.
	АР	<u>3</u>	Cole, M.S. a Surface Mo 4-11.	and Count T	aulfield, T. echnology	. "A F , Sur	Review of Available face Mount Technol	Ball Grid Ar logy Associ	ray (Beation,	GA) Packac January 19	ges", Journal of 96, Vol. 9, pp.
	AQ-	<u>3</u>	Cole, M.S. a Conference California, p	and C Proc pp. 14	aulfield, T. eedings, S 47-153.	., "Ba urfac	ıll Grid Array Packaç e Mount Internation	ging", Surfa nal, August	ice Moi 28-Se	unt Interna ptember1,	itional 1994, San Jose,
MC	AR	<u>3</u>	Dobers, M. Advanced F and 32.	and S Packa	Seyffert, M ging, IHS I	l., "Lo Publis	ow Cost MCMs: BGA shing Group, Septen	s Provide anber/Octob	Fine-l er 199	Pitch Alterr 4, Vol. 3, N	native", No. 5, pp. 28, 30
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	AK4									Yes No
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	AO	Edwards, of PQFP, Technolog	D. et a Therm gy Con	al., "The Ef ally Enhand ference, IE	fect (ced P EEE, I	of Internal Package I QFP, LOC and BGA F May 21-24, 1995, Las	Delaminati Packages", s Vegas, N	ons on 45th E V, pp.	the Therm Electronic (285-292.	nal Performance Components &
	АР	4 Packages	". Jour	"Designed nal of Surfa ol. 9, pp. 3	ace N	eriment to Determine Mount Technology, Si	e Attachme urface Moi	ent Rel unt Tec	iability Driv chnology A	vers for PBGA ssociation,
	AQ	Ewanich, 1995 Inte pp. 588-5	J. et a rnation 94.	l., "Develop nal Electror	pmer nics F	nt of a Tab (TCP) Ball Packaging Conference	l Grid Arra e, San Die	y Packa go, CA,	age", Proce Septembe	eedings of the er 24-27, 1995,
MC	AR	Fauser, S No. 2, pp	. et al, . 36-38	"High Pin- 3 and 40.	Coun	t PBGA Assembly", C	Circuits Ass	embly,	February	1995, Vol 6,
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m	,	AN .	<u>5</u>	Fauser, Su Cause Anal Mount Inte	zanne ysis", rnatic	et al., "Hi Surface N onal, Augu	igh Pi Iount Ist 28-	n Count PBGA Assem International, Procee September1, 1994, S	ibly: Solde edings of San Jose,	er Defe The Te Califor	ect Failure echnical Pro nia, pp. 16	Modes and Root ogram, Surface 19-174.
		AO	<u>5</u>	Ferguson, No. 2, pp.	M. "Eı 54, 56	nsuring Hi 5 and 58.	gh-Yie	eld BGA Assembly", C	Circuits As	sembly	/, February	1995, Vol. 6,
		АР	<u>5</u>	Freda, M., Cahners Pu	"Lami ıblishi	inate Tech ng Compa	inolog iny, O	y for IC Packaging", ctober 1995, Vol. 35	Electronio , No. 11,	c Packa pp. S4	aging & Pro -S5.	oduction,
		AQ	<u>5</u>	Freedman, M., "Package Size and Pin-Out Standardization", Ball Grid Array National Symposium, March 29-30, 1995, 7 pages.								
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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

ATTY. DOCKET NO. APPLICATION NO. 1875.0370000 09/849,537

APPLICANT

Zhang et al.

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		AO	<u>6</u>	Freyman, B Conference	. et al Proce	I., "The Mo eedings, Sa	ove to an Jos	Perimeter Plastic se, CA, August 29-	BGAs", Sur 31, 1995, p	face Mo	ount Intern -382.	ational
		АР	<u>6</u>	Freyman, B Texas, Mar	., "Tre ch 29-	ends in Pla -30, 1995,	stic B 45 pa	GA Packaging," Bages.	all Grid Arra	y Natio	onal Sympo	sium, Dallas,
		AQ	<u>6</u>	Gilleo, K., " IHS Publish	Electro ing G	onic Polym roup, Sept	ners: I embe	Die Attach and Ori r/October 1994, V	ented Z-Ax ol. 3, No. 5	is Films , pp. 3	s", Advance 7-38, 40 an	d Packaging, id 42.
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ATTY. DOCKET NO. 1875.0370000 APPLICATION NO. 09/849,537

	FORM PTO-1449 SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT						APPLICANT Zhang et al.				
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	AQ	<u>7</u>	Heitmann, Advanced 103.	R., "A Packa	A Direct Att ging, IHS	tach I Publis	Evolution: TAB, COB shing Group, July/Au	and F gust 1	lip Chip As 994, Vol. 3	sembly Cha 3, No. 4, pp	allenges", b. 95-99 and
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MC	AR	<u>8</u>	Hundt, M. et al., "Thermal Enhancements of Ball Grid Arrays", National Electronic Packaging and Production Conference West '95, Reed Exhibition Companies, Anaheim, CA, February 29, 1996, pp. 702-711.								ic Packaging February 25-
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MC	AN	<u>13</u>	Matthew, L Packaging,	.C. et IHS I	al., "Area Publishing	Arra Grou	y Packaging: KGD i p, July/August 1994	n a Chip-Si; 4, pp. 91-9	zed Pac 4.	ckage", Adv	vanced	
	AO	<u>13</u>	Mawer, A. o Internation 1994, San	et al., al Co Jose,	, "Plastic B nference P California,	GA S roce pp.	older Joint Reliabilit edings, Surface Moi 239-251.	y Considera unt Interna	ations", tional,	, Surface M August 28-	lount September1,	
	АР	<u>13</u>	Mazzullo, T Technology	. and Mag	Schaertl, azine, Feb	L., "H ruary	How IC Packages Af 1995, Vol. 9, No. 2	fect PCB De 2, pp. 114-	esign", 116.	Surface M	ount	
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	AQ .	<u>14</u>	Olachea, G Production	., "Ma (Spec	naging He cial Supple	eat: / ement	\ Focus on Power IC); Cahners Publishing	Packagin GCompan	g", Ele y, Nov	ctronic Pac ember 199	kaging & 94, pp. 26-28.		
	AR	14	"Pad Array Improves Density", Electronic Packaging & Production, Cahners Publishing Company, May 1992, pp. 25-26.										
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	AO	<u>15</u>	Ramirez, C Array", Sui August 28-	and face Septe	Fauser, S Mount Int ember1, 1	5., "Fati ernatic 994, S	gue Life Comparison nal Conference Proc an Jose, California, p	of The Freedings, op. 258-20	erimet Surfac 56.	er and Full e Mount In	Plastic Ball Grid ternational,			
	AP	<u>15</u>	Rogren, P. Production	, "MC Conf	M-L Built (erence W	on Ball est '94	Grid Array Formats" Anaheim, California	', Nationa i, pp. 127	l Electi 7-1282	ronic Packa 2.	ging and			
	AQ	<u>15</u>	Rooks, S., Internation California,	Rooks, S., "X-Ray Inspection of Flip Chip Attach Using Digital Tomosynthesis", Surface Mount International, Proceedings of The Technical Program, August 28-September1, 1994, San Jose, California, pp. 195-202.										
	AR	<u>15</u>	Rukavina, Symposiun	J., "A n, Da	ttachment llas, Texas	t Metho s, Marc	odologies: Ball Grid A h 29-30, 1995, 37 pa	Array Tecl ages.	nnolog	y", Ball Grid	d Array National			
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		AO	<u>16</u>	Sakaguchi,	H., "B	GA Mount	ingTe	chnology," pgs. 1-	4, date	and source	e unknown.		
		АР	<u>16</u>	Schmolze, C Packaging 8	and Proc	Fraser, A. Juction, Ja	., "SP: nuary	ICE Modeling Helps 1995, pp. 50-52.	s Enhan	ce BGA Pe	erformance"	, Electronic	
		AQ ·	<u>16</u>	Semiconduc document s	Semiconductor Group Package Outlines Reference Guide, Texas Instruments, 1995, entire document submitted.								
	AR 16 Shimizu, J., "Plastic Ball Grid Array Coplanrity", Surface Mount International Conference, San Jose, California, August 31-September 2, 1993, pp. 86-91.												
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	AO	<u>17</u>	Sirois, L., " Advanced I	Dispe Packa	ensing for Iging, IHS	BGA: 7 Publis	Automated Liquid Disp hing Group, May/June	ensing i 1995, p	n a Hig op. 38	gh-Density and 41.	Environment",	
	АР	<u>17</u>	Solberg, V. Surface Fin Texas, Mar	, "Int ish o ch 29	erconnect n SMT Ass 9-30, 1995	ion St sembly 5, 10 p	ructure Preparation: I Process Yield", Ball G ages.	mpact o	of Mate y Natic	erial Handlir onal Sympo	ng and PCB sium, Dallas	
	Q	<u>17</u>	"Survival o unknown.	f the	Fittest", A	.dvanc	ed Packaging, IHS Pub	olishing (Group,	March/Apr	il 1995, page	
	AR	<u>17</u>	Tuck, J., "E 24, 26, and	3GA T 1 28.	echnology	y Bran	ches Out", Circuits Ass	sembly,	Februa	ary 1995, V	ol. 6, No. 2, pp.	
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	AO	<u>18</u>	Vardaman, National Ele Companies,	E. J. ectror Ana	and Crowl nic Packag heim, CA,	ley, R ing ai Febru	.T., "Worldwide Trends I nd Production Conferenc lary 25-29, 1996, pp. 69	n Ball Grid / e West '96, 9-701.	Array Devel Reed Exhib	opments", iition
	АР	18	Walshak, D Electronic P Anaheim, C	. and acka alifor	Hashemi, ging and P nia, Febru	H., " Production 2	Thermal Modeling of a Modeling	1ultichip BGA 94, Reed Ext 66-1276.	A Package", nibition Con	National npanies,
	AQ	<u>18</u>	Walshak, D Ceramic an Internation	. and d Tap al, Au	Hashemi, pe BGAs", ugust 28-S	H., " Surfa epter	BGA Technology: Currer ce Mount International C nber1, 1994, San Jose, C	nt and Future Conference F California, pp	e Direction Proceedings D. 157-163.	for Plastic, , Surface Mount
	AR	<u>18</u>	Xie, H. et a Notebooks'' 21-24, 199	l., "T , 45t s, pp	hermal Sol h Electron . 201-210.	lution ic Cor	s to Pentium Processors nponents & Technology	in TCP in No Conference,	otebooks a IEEE, Las	nd Sub- Vegas, NV, May
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	AO	<u>19</u>	Zamborsky 2, pp. 60, 6	, E., ' 52-64	'BGAs in th	ne Ass	sembly Process", Cir	cuits Asse	mbly, I	ebruary 19	95, Vol. 6, No.	
	АР	<u>19</u>	Zimerman, Internation 1994, San	M., " al Co Jose,	High Perfo nference F California,	orman Procee pp. 1	ce BGA Molded Pacedings, Surface Mou 75-180.	kages for I Int Interna	MCM A tional,	pplication", August 28-	Surface Mount September1,	
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	AR	Houghten, J.L., "Plastic Ball-Grid Arrays Continue To Evolve", Electronic Design, February 6, 1995, pp. 141-146.										
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